# **Panasonic**

## DB2W60400L

## Silicon epitaxial planar type

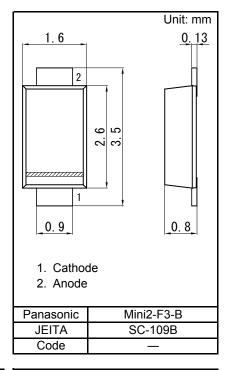
### For rectification

#### ■ Features

- Small reverse current IR
- Forward current (Average) IF(AV) = 2 A rectification is possible
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: CD

#### ■ Packaging

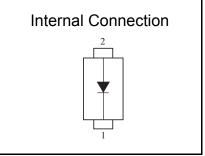
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	60	V
Peak forward current *1	IF(AV)	2	Α
Non-repetitive peak forward surge current *2	IFSM	30	Α
Junction temperature *1	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note: \*1 TI = 80 °C



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<sup>\*2 50</sup> Hz sine wave 1 cycle (Non-repetitive peak current)

Schottky Barrier Diode

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### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

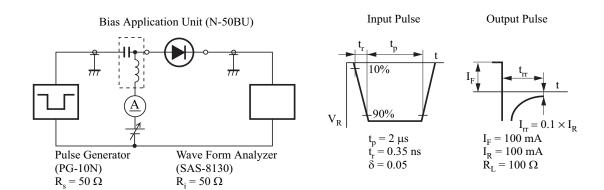
Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Forward voltage	VF	IF = 2 A		0.59	0.66	V	
Reverse current	IR	VR = 60 V			300	μΑ	
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		38		pF	
Reverse recovery time *1	trr	IF = IR = 100 mA Irr = 0.1 × IR, RL = 100 $\Omega$		12		ns	

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*1 trr test circuit

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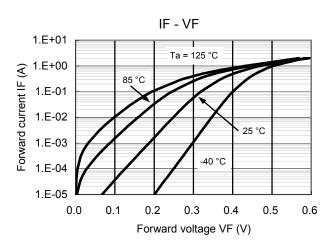
: 2013-04-27

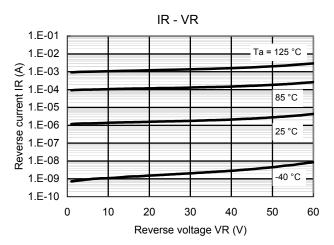
Revised

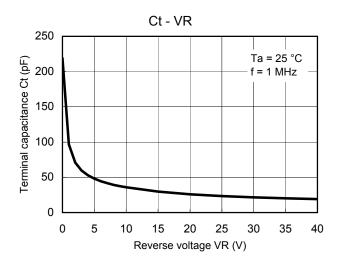


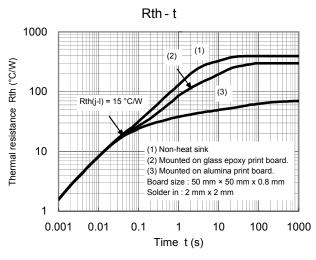
Schottky Barrier Diode DB2W60400L

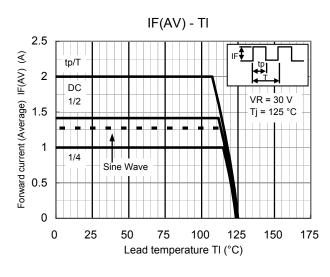
## Technical Data (reference)

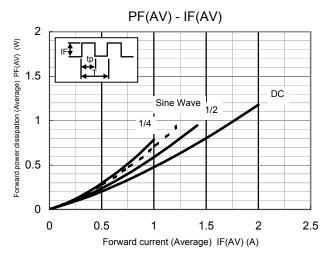












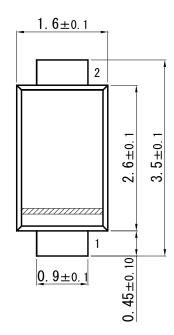
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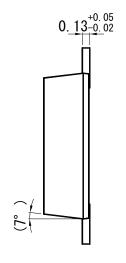
Schottky Barrier Diode

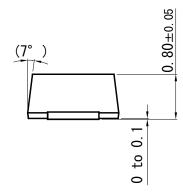
### DB2W60400L

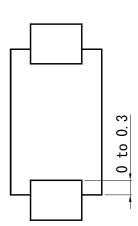
Mini2-F3-B

Unit: mm

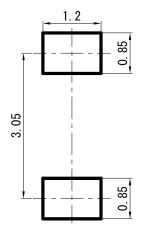








■ Land Pattern (Reference) (Unit: mm)



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